ABSTRACT OF THE DISCLOSURE

An IC device includes a die and a first package interposer stacked over a second package interposer. The IC device includes a first conductive connection from a first bond pad of the die directly to a bond pad of the first interposer and a second conductive connection from a second bond pad of the die directly to a bond pad of the second interposer. Another IC device includes a second die stacked over a separate first die and a first package interposer stacked over a separate second package interposer. The first die is stacked over the first interposer. A first conductive connection exists from a bond pad of the first die directly to a bond pad of the first interposer and a second conductive connection exists from a bond pad of the second die directly to a bond pad of the second interposer.

FIGURE 6